

#### QuickLogic QL80FC Programmable Fibre Channel ENDEC

#### **FEATURES**

- ANSI Fibre Channel (FC) compatibility
- Data rates up to 2.5 Gb/s supported
- 2.5Gb/s Simplex (200 MByte/s) or Duplex (400 MByte/s) Mode
- Compatible with standard SERDES components
- 32 bit synchronous FIFO system interface
- Tx and Rx internal FIFO for system applications without external FIFOs
- Selectable 20-bit/10-bit encoded transmission character interface to SERDES
- 8b/10b Encoding/Decoding
- CRC Calculation and checking per FC standard
- Fibre Channel Loss of Synchronization (LOS) state machine
- Support for arbitrated loops
- IntraFrame idles support for proprietary links
- "Raw" data path for the injection of encoding and CRC errors into the bitsteam for use in testing link error handling functions
- 3.3V operating voltage
- 3.3V CMOS I/O, 5.0V CMOS tolerant inputs
- 208 PQFP and 456 PBGA packages available

#### **EXTENDED FEATURES**

Extended features that can be designed into the user customizable logic:

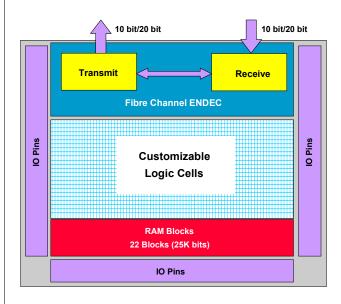
- Fibre Channel Link Control State Machine (LCSM)
- RRDY credit management for link flow control
- Microprocessor interface to configure various link modes
- BIST functions support link bit error rate measurements

## **DUAL PORT SRAM**

- 22 blocks (total of 25,344 bits) of dual-port RAM
- Configurable as RAM, ROM or FIFO
- Can be configured as two internal FIFOs of up to 352 x 36 in size
- Configurable RAM array sizes (by 2, 4, 9, 18)
- <5ns access times, 160+Mhz FIFOs

#### HIGH SPEED CUSTOMIZABLE LOGIC

- Up to 269 customizable I/O pins
- 751 Logic cells
- 300 MHz 16-bit counters, 400 MHz Data paths
- Mux-Based architecture; non-volatile technology
- Completely customizable for any digital application



Fibre Channel Block Diagram



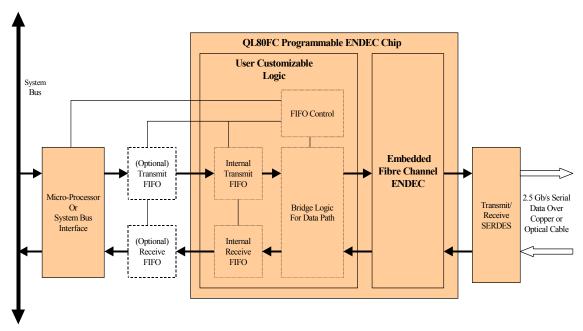


FIGURE 1. System Level Diagram

#### GENERAL DESCRIPTION

The QL80FC device in the QuickLogic QuickFC ESP (Embedded Standard Product) family provides a completely integrated configurable Fibre Channel Encoder/Decoder interface solution combined with customizable logic. This device provides a means to receive and transmit high-speed serial data and implement a Fibre Channel Link interface or any proprietary high-speed serial link.

The chip is divided into two main portions, an embedded design and a customizable design. The embedded design contains the built in functionality of Fibre Channel's FC-1 and FC-2 layers, which the system designer uses as a standard product. This portion can not be modified. As such, all functionality and timing requirements have been verified in hardware and are guaranteed.

The customizable portion consists of user customizable system gates, and interfaces directly to the embedded portion of the chip. These gates may be programmed to implement glue logic to other bus standards such as PCI or SCSI. They can also be programmed with Fibre Channel Upper Layer Protocols. Of course, the designer may choose to modify Upper Layer Protocols for customization. In this way, the

QuickLogic QL80FC provides the embedded systems designer with an easy to use and cost effective solution for embedded serial applications.

#### FIBRE CHANNEL APPLICATIONS

The QL80FC ENDEC is a high performance encoder/decoder designed for use in conjunction with Gb/s SERDES transmitter/receiver chips. These chips, when combined with internal FIFO buffer memory, can be used to build a complete serial link. Optional, external FIFOs can be used in place of the available internal FIFOs to extend buffering to sizes beyond 352 words.

The embedded ENDEC is a full duplex design with an encoder section for transmission and a decoder section for reception. The transmitter/encoder section accepts a 4-byte user data word, encodes each byte into a 10-bit transmission character and outputs transmission characters to the SERDES transmitter. This equals two 10-bit characters per clock (one 10-bit character per clock in 10-bit mode). The receiver/decoder section accepts two 10-bit transmission characters.



acters from the SERDES receiver (one 10-bit character in 10-bit mode), decodes them, and outputs a 4-byte user data word.

The QL80FC has a system interface that emulates a synchronous FIFO for ease of use. FIFOs allow maximum sustained performance of 400 MB/s running a full duplex link. Their function is to handle the asynchronous interface between the bus data rate and the different serial data rates, and handle phase and frequency differences inherent in serial links. Internal FIFOs of  $352 \times 36$  or external FIFOs can be used to expand the buffering to accommodate multiple frames.

The QL80FC includes the hardware necessary for packetized data protection. Framing functions are provided via Fibre Channel compliant command words (ordered sets) for Start of Frame and End of Frame. CRC generation and data frame verification protect the Fibre Channel frame header and data field when these framing functions are used.

The device provides a microprocessor interface that allows the user to manage the serial link. Signals are also provided to decode serial link error conditions and differentiate between data and commands. The QL80FC implements link synchronization with the

SERDES chip through the Loss of Synchronization State Machine (LOS) as required by the ANSI FC-PH specification. The LOS manages receiver word synchronization with the RxComDet (comma detect) signal.

The QL80FC is a versatile part that allows the system designer to create proprietary or Fibre Channel compliant serial links by taking advantage of some, or all, of the Fiber Channel compliant features. It has a number of useful features for system designers of proprietary links. One such feature is the ability to send intraframe IDLEs. These characters are automatically sent if the FIFO is empty, but they do not affect the CRC. In this mode the QL80FC allows simple interfacing to systems where the flow of data may be interrupted.

# EMBEDDED DESIGN FUNCTIONAL DESCRIPTION

The embedded FC-1 and FC-2 layers are divided into two functional groupings: the Transmit data path and the Receive data path. A functional diagram for the Transmit path is included in Figure 2.

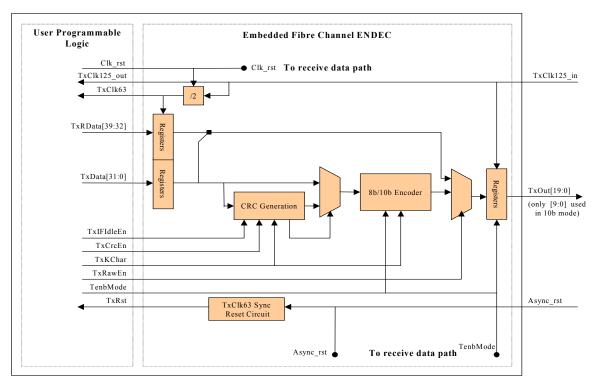


FIGURE 2. Customizable ENDEC Chip Functional Block Diagram - Transmit and LCSM Data Paths



#### TRANSMIT DATA PATH

When the transmit data path is in standard operation (TxRawEn not asserted) the chip will latch an unencoded, Fibre Channel, 32-bit word on inputs TxData[31:0]. This data then passes on to the 8b/10b encoder, which creates a 40-bit encoded Fibre Channel word. The encoder will encode the most significant character as a command character if the TxKChar input line is asserted. This word is registered and passed to the SERDES in 20-bit chunks (10 bit chunks if 10 bit mode is enabled) on the TxOut signal lines.

Asserting the TxCrcEn signal enables the CRC Generation block. This block will automatically detect the SOF ordered set and begin CRC generation using the ANSI specified CRC polynomial. It will continue until an EOF or any other FC ordered set is encountered (unless TxIFIdleEn is asserted, then the IDLE ordered set will be ignored by the CRC generator). It then inserts the CRC value into the data path for transmission to the SERDES.

The TxRawEn signal enables the raw transmit data path when asserted. In this mode, the 8 bits of TxR-Data is concatenated onto the 32 bits of the TxData signal to create a 40-bit wide data path. The CRC generation and 8b/10b encoder blocks are bypassed and the "raw" data latched at the inputs is passed directly to the output registers that drive the SER-DES. This mode is useful for testing the error handling capabilities of the serial link by providing the systems designer a way to intentionally introduce errors into the serial bit stream.

The TxIFIdleEn (Intra-Frame Idle Enable) input enables the use of Fibre Channel IDLE words within a Frame. When this signal is asserted, IDLE words present within a data frame will not affect the value generated by the CRC block. This feature is useful in custom FC designs where it is desired to suspend the transmission of a frame for a period of time and then resume later.

The use of external FIFOs is optional. There is enough RAM on the ENDEC chip to be configured into two  $352 \times 36$  FIFOs. If FIFOs of this size are all that is required, external FIFOs would not be needed. Synchronous read and writes directly from the system bus without a FIFO is also possible.

Two clock signals are supplied to the customizable logic on high speed, low skew clock networks: TxClk125 and TxClk63. TxClk125 is a clock running at a maximum speed of 125 MHz, and represents the "full speed" of the Oscillator being used to clock the transmit data path. The input that drives this signal is also used to clock the SERDES chip. The TxClk63 clock signal operates at half the speed of the TxClk125 clock. You will most likely want to use the TxClk63 signal to clock your FIFOs and customizable logic. Of course, these signals can be routed off-chip through the customizable I/O.

The Async\_rst pin accepts an asynchronous, active high reset signal. Circuitry takes this signal and synchronizes it with the TxClk63 clock. This synchronous reset signal, TxRst, is used to set or clear flipflops in the transmit data path. It is made available to the user programmable logic for the same purpose on a high speed, low skew network

The Clk\_rst input stops the TxClk63 clock when this signal is asserted. This signal was added primarily to facilitate simulation. Clk\_rst may be permanently grounded in hardware.



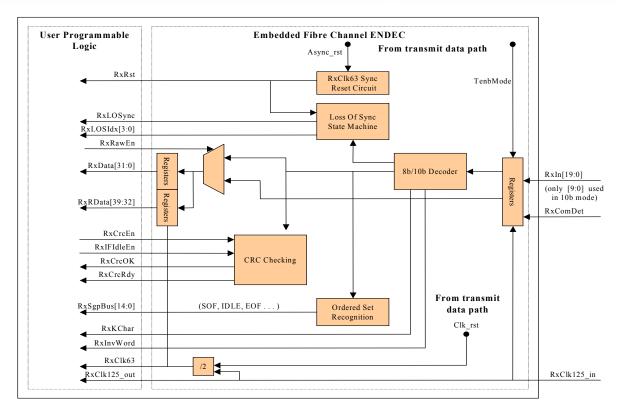


FIGURE 3. .Customizable ENDEC Chip Functional Block Diagram - Receive Data Path

#### RECEIVE DATA PATH

The receive data path receives encoded data from an on-board SERDES, decodes it and passes the resulting data to the customizable section of the chip. A functional block diagram of the receive data path is shown in Figure 3.

The RxClk125 signal latches 20 bits (10 bits when 10-bit mode is enabled) of data from the SERDES into the RxIn input registers on the positive edge of the clock. The RxClk125 signal is made available to the customizable section. RxClk125 is divided by two and made available to the customizable section on the RxClk63 signal line. Both clocks use a high speed, low skew clock network. Again you will most likely want to use the RxClk63 signal to clock all registers and FIFOs in the receive data path. Registers using RxClk125 and RxClk63 should be sensitive to the rising edge of these clocks.

Once the data on the RxIn signal lines is latched into the input registers, the data is passed on to the 8b/10b decoder. Under standard operation, (input RxRa-

wEn is low), the data is decoded into 4, 8-bit characters and the resulting Fibre Channel word is placed on the RxData[31:0] output signals. RxRData is not used under normal operation. If the decoder detects a Fibre Channel comma character in the most significant character of the word, the RxKChar signal line will be asserted.

When the RxCrcEn signal is asserted the CRC checking logic will function. The CRC logic will automatically detect a SOF word and begin performing CRC division on the next word in the data stream using the ANSI specified CRC polynomial for Fibre Channel. When an EOF word or any other FC ordered set is detected (unless RxIFIdleEn is asserted, then the IDLE ordered set will be ignored by the CRC checker) the CRC will assert the RxCrcRdy signal for one cycle of the RxClk63 clock. If the remainder for the division is zero, the RxCrcOK signal line will also be asserted during this same cycle.



When the RxRawEn signal is asserted the "raw" data path will be enabled for the receive circuit. With the "raw" data path enabled, the data received from the SERDES does not pass through the 8b/10b decoder or the CRC checking blocks. Instead it is routed directly to the output registers and is made available to the customizable section of the chip on signal lines RxRData and RxData. This mode is useful for testing the serial link.

The Loss of Synchronization State machine is responsible for achieving character synchronization on the data being sent from the SERDES. When the Rst signal is asserted, the LOSSM goes to the "loss of synchronization" state. In this state the RxLOSync signal will be asserted. After the reception of three valid command characters, the state machine will proceed to the "synchronization acquired" state and the RxLOSync signal is de-asserted. After the reception of 4 successive invalid characters the state machine will return to the "Loss of Synchronization" state. The value on the RxLOSIdx bus indicates the state of LOSSM.

The ordered set recognition block detects Fibre Channel ordered sets and asserts one signal line in the RxSgpBus bus corresponding to the ordered set detected. All 15 Fibre Channel ordered set types are detected including SOF, EOF and IDLE. There is a list of ordered sets detected by the ordered set recognition circuitry in Table 1.

There are two signals used to indicate that a word having a decoding error of some kind is present on the RxData outputs. When RxInvChar is asserted a word with an invalid 10-bit representation is present on the RxData signal lines. RxRDErr indicates an invalid running disparity was detected on the currently available RxData word.

The Async\_rst pin accepts an asynchronous, active high reset signal. Circuitry takes this signal and synchronizes it with the RxClk63 clock. This synchronous reset signal, RxRst, is used to set or clear flipflops in the receive data path. It is made available to the user programmable logic for the same purpose on a high speed, low skew network.

The Clk\_rst input stops the RxClk63 clock when this signal is asserted. This signal was added primarily to facilitate simulation. Clk\_rst may be permanently grounded in hardware.



## **RECOGNIZED ORDERED SETS**

Beginning RD	Identifier	Ordered Set Code	Hex Equivalent	RxSgpBus Signal Line Asserted
-	SOFc1	K28.5 D21.5 D23.0 D23.0	BC B5 17 17	[0]
-	SOFi1	K28.5 D21.5 D23.2 D23.2	BC B5 57 57	[0]
-	SOFn1	K28.5 D21.5 D23.1 D23.1	BC B5 37 37	[0]
-	SOFi2	K28.5 D21.5 D21.2 D21.1	BC B5 55 55	[0]
-	SOFn2	K28.5 D21.5 D21.1 D21.1	BC B5 35 35	[0]
-	SOFi3	K28.5 D21.5 D22.2 D22.2	BC B5 56 56	[0]
-	SOFn3	K28.5 D21.5 D22.1 D22.1	BC B5 36 36	[0]
-	SOFf	K28.5 D21.5 D24.2 D24.2	BC B5 58 58	[0]
-	EOFt	K28.5 D21.4 D21.3 D21.3	BC 95 75 75	[1]
+	EOFt	K28.5 D21.5 D21.3 D21.3	BC B5 75 75	[1]
-	EOFdt	K28.5 D21.4 D21.4 D21.4	BC 95 95 95	[1]
+	EOFdt	K28.5 D21.5 D21.4 D21.4	BC B5 95 95	[1]
-	EOFa	K28.5 D21.4 D21.7 D21.7	BC 95 F5 F5	[1]
+	EOFa	K28.5 D21.5 D21.7 D21.7	BC B5 F5 F5	[1]
-	EOFn	K28.5 D21.4 D21.6 D21.6	BC 95 D5 D5	[1]
+	EOFn	K28.5 D21.5 D21.6 D21.6	BC B5 D5 D5	[1]
-	EOFdti	K28.5 D10.4 D21.4 D21.4	BC 8A 95 95	[1]
+	EOFdti	K28.5 D10.5 D21.4 D21.4	BC AA 95 95	[1]
-	EOFni	K28.5 D10.4 D21.6 D21.6	BC 8A D5 D5	[1]
+	EOFni	K28.5 D10.5 D21.6 D21.6	BC AA D5 D5	[1]
-	IDLE	K28.5 D21.4 D21.5 D21.5	BC 95 B5 B5	[2]
+	IDLE*	K28.5 D21.5 D21.5 D21.5	BC B5 B5 B5	[2]
-	R RDY	K28.5 D21.4 D10.2 D10.2	BC 95 4A 4A	[3]
-	OLS	K28.5 K21.1 D10.4 D21.2	BC 35 8A 55	[4]
-	NOS	K28.5 D21.2 D31.5 D5.2	BC 55 BF 45	[5]
-	LR	K28.5 D9.2 D31.5 D9.2	BC 49 BF 49	[6]
-	LRR	K28.5 D21.1 D31.5 D9.2	BC 35 BF 49	[7]
-	ARBx	K28.5 D20.4 AL_PA AL_PA	BC 4A xx xx	[8]
-	ARB(F0)	K28.4 D20.4 D16.7 D16.7	BC 4A F0 F0	[8]
-	OPNyx	K28.5 D17.4 AL_PD AL_PS	BC 91 yy xx	[9]
-	OPNyy	K28.5 D17.4 AL_PD AL_PD	BC 91 yy yy	[9]
-	OPNfr	K28.5 D17.4 D31.7 D31.7	BC 91 FF FF	[9]
-	OPNyr	K28.5 D17.4 AL_PD D31.7	BC 91 yy FF	[9]
-	CLS	K28.5 D5.4 D21.5 D21.5	BC 85 B5 B5	[10]
-	MRKtx	K28.5 D31.2 MK_TP AL_PS	BC 5F tt xx	[11]
-	LIP(F7,F7)	K28.5 D21.0 D23.7 D23.7	BC 15 F7 F7	[12]
-	LIP(F8,F7)	K28.5 D21.0 D24.7 D23.7	BC 15 F8 F7	[12]
-	LIP(F7,x)	K28.5 D21.0 D23.7 AL_PS	BC 15 F7 xx	[12]
-	LIP(F8,x)	K28.5 D21.0 D24.7 AL_PS	BC 15 F8 xx	[12]
-	LIP(y,x)	K28.5 D21.0 AL_PD AL_PS	BC 15 yy xx	[12]
-	LPEyx	K28.5 D5.0 AL_PD AL_PS	BC 05 yy xx	[13]
-	LPEfx	K28.5 D5.0 D31.7 AL_PS	BC 05 FF xx	[13]
-	LPByx	K28.5 D9.0 AL_PD AL_PS	BC 09 yy xx	[14]

#### **TABLE 1. Table of Recognized Ordered Sets**



<sup>\*</sup> Only recognized when RxIFIdleEn is asserted

## **SIGNAL DEFINITIONS**

#### **Dedicated I/O Pins**

Async_rst	input	active high, asynchronous reset
TxOut[19:0]	output	data transmitted to SERDES (only lines [9:0] are used in 10 bit mode)
TxClk125_in	input	transmit clock up to 125 MHz
RxIn[19:0]	input	data received from SERDES
RxClk125_in	input	receive clock up to 125 MHz
RxComDet	input	Fibre Channel comma character detected
ResIn[2:0]	input	reserved for QuickLogic use, hold low or high

# **Customizable Interface Signals**

TenbMode	input	enables 10 bit interface to SERDES when asserted			
Clk rst	Input	Stops TxClk63 and RxClk63 when high. Tie Low.			
TxRst	output	active high reset signal for transmit path, synchronous with TxClk63			
TxData[31:0]	input	32 bit Fibre Channel word to be encoded for transmit path			
TxRData[39:32]	input	only used when TxRawEn is asserted. Combines with TxData to			
	-	construct 40 bit raw data for transmit path			
TxCrcEn	input	enables CRC error value generation when asserted			
TxIFIdleEn	Input	enables Intra-Frame IDLE support for transmit path when asserted			
TxRawEn	input	select between raw and encoded data modes for transmit data path			
TxKChar	input	indicates that the most significant byte of data word is a K character			
TxClk125	output	full speed transmit clock up to 125 MHz (use the rising edge)			
TxClk63	output	half speed transmit clock up to 63 MHz (use the rising edge)			
RxData[31:0]	output	32 bit Fibre Channel word decoded by the ENDEC receive path.			
RxRData[39:32]	output	only used when RxRawEn is asserted. Combines with RxData to			
		construct 40 bit raw data through the ENDEC receive path			
RxRawEn	input	select between raw and encoded data modes for receive data path			
RxKChar	output	asserted when most significant byte of data word is a K character			
RxSgpBus[14:0]	output	bus indicating when an ordered set is detected. One signal line is asserted			
		corresponding to the type of ordered set detected:			
		[0] – SOF [5] – NOS [10] – CLS			
		[1] – EOF [6] – LR [11] – MRK			
		[2] – IDLE [7] – LRR [12] – LIP			
		[3] – R_RDY [8] – ARB [13] – LPE			
		[4] – OLS [9] – OPN [14] – LPB			
RxCrcRdy	output	asserted when available data is a CRC word			
RxCrcOK	output	asserted when CRC remainder is zero			
RxCrcEn	input	enables CRC error checking for the receive data path when asserted			
RxIFIdleEn	input	enables Intra-Frame IDLE support for receive path when asserted			
RxLOSync	output	asserted when bit synchronization with the SERDES has been lost			
RxLOSIdx[3:0]	output	index indicating state of Loss of Sync state machine			
RxInvChar	output	asserted when available data has an invalid encoding error			
RxClk125	output	full speed receive clock up to 125 MHz (use the rising edge)			
RxClk63	output	half speed receive clock up to 63 MHz (use the rising edge)			
RxRst	output	active high reset signal for receive data path, synchronous with RxClk63			
ResOut[2:0]	output	reserved for QuickLogic use, do not connect to these outputs			



#### ARRAY OF LOGIC CELLS

A wide range of additional features complements the QL80FC device. The FPGA portion of the device is 5-volt and 3.3-volt compliant and can perform high-speed logic functions such as 160 MHz FIFOs. I/O pins provide individually controlled output enables, dedicated input/feedback registers, and full JTAG capability for boundary scan and test. In addition, the QL80FC device provides the benefits of non-volatility, high design security, immediate functionality on power-up, and a single chip solution.

The QL80FC customizable logic architecture consists of an array of user-configurable logic building blocks, called logic cells, set beneath a grid of metal wiring channels similar to those of a gate array. Through ViaLink® elements located at the wire intersections, the output(s) of any cell may be programmed to connect to the input(s) of any other cell. Using the customizable logic in the QL80FC, designers can quickly and easily customize their "back-end" design for any number of applications.

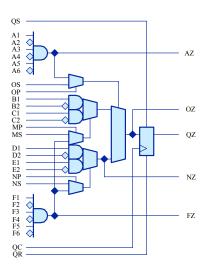


FIGURE 4. Logic Cell

#### RAM MODULE FEATURES

The QL80FC device has 22 1,152-bit RAM modules, for a total of 25,344 RAM bits. Using two "mode" pins, designers can configure each module into 64 (deep) x18 (wide), 128x9, 256x4, or 512x2 blocks. See the table below. The blocks are also easily cascadable to increase their effective width or depth.

Mode:	Address Buses [a:0]	Data Buses [w:0]
64x18	[5:0]	[17:0]
128x9	[6:0]	[8:0]
256x4	[7:0]	[3:0]
512x2	[8:0]	[1:0]

The RAM modules are "dual-ported", with completely independent READ and WRITE ports and separate READ and WRITE clocks. The READ ports support asynchronous and synchronous operation, while the WRITE ports support synchronous operation. Each port has 18 data lines and 9 address lines, allowing word lengths of up to 18 bits and address spaces of up to 512 words. Depending on the mode selected, however, some higher order data or address lines may not be used.



The Write Enable (WE) line acts as a clock enable for synchronous write operation. The Read Enable (RE) acts as a clock enable for synchronous READ operation (ASYNCRD input low), or as a flow-through enable for asynchronous READ operation (ASYNCRD input high).

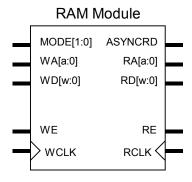


FIGURE 5. RAM Module

Designers can cascade multiple RAM modules to increase the depth or width allowed in single modules by connecting corresponding address lines together and dividing the words between modules. This approach allows up to 512-deep configurations as large as 16 bits wide in the QL80FC device.

A similar technique can be used to create depths greater than 512 words. In this case, address signals higher than the eighth bit are encoded onto the write enable (WE) input for WRITE operations. The READ data outputs are multiplexed together using encoded higher READ address bits for the multiplexer SELECT signals.

#### JTAG SUPPORT

JTAG pins support IEEE standard 1149.1a to provide boundary scan capability for the QL80FC device. Six pins are dedicated to JTAG and programming functions on each QL80FC device, and are unavailable for general design input and output sig-

nals. TDI, TDO, TCK, TMS, and TRSTB are JTAG pins. A sixth pin, STM, is used only for programming.

#### **DEVELOPMENT TOOLS**

Software support for the QL80FC device is available through the QuickWorks<sup>TM</sup> development package. This turnkey PC-based QuickWorks package, shown in Figure 6, provides a complete ESP software solution with design entry, logic synthesis, place and route, and simulation. QuickWorks includes VHDL, Verilog, schematic, and mixed-mode entry with fast and efficient logic synthesis provided by the integrated Synplicity Synplify Lite<sup>TM</sup> tool, specially tuned to take advantage of the QL80FC architecture. QuickWorks also provides functional and timing simulation for guaranteed timing and source-level debugging.

The UNIX-based Quick $Tools^{TM}$  package is a subset of QuickWorks and provides a solution for designers who use schematic-only design flow or third-party tools for design entry, synthesis, or simulation.

# QuickWorksDesign Software Third Party Design Entry & Synthesis Tools WHDL/ Verilog Turbo HDL Editor Mixed-Mode Design Simulator Simulator Simulator Simulator Simulator

FIGURE 6. QuickWorks Tool Suite



# **QL80FC External Device Pins**

Туре	Description
IN	Input. A standard input-only signal.
OUT	Totem pole output. A standard active output driver.
T/S	Tri-state. A bi-directional, tri-state input/output pin.
S/T/S	Sustained Tri-state. An active low tri-state signal driven by one PCI agent at a time. It must be driven high for at least one clock before being disabled (set to Hi-Z). A pull-up needs to be provided by the PCI system central resource to sustain the inactive state once the active driver has released the signal.
O/D	Open Drain. Allows multiple devices to share this pin as a wired-or.

D: (D	_	
Pin/Bus Name	Type	Function
VCC	IN	Supply pin. Tie to 3.3V supply.
VCCIO	IN	Supply pin for I/O. Set to 3.3V for 3.3V I/O, 5V for 5.0V compliant I/O.
GND	IN	Ground pin. Tie to GND on the PCB.
I/O	T/S	Programmable Input/Output/Tri-State/Bi-directional Pin.
GLCK/I	IN	Programmable Global Network or Input-only pin. Tie to VCC or GND if unused.
ACLK/I	IN	Programmable Array Network or Inputonly pin. Tie to VCC or GND if unused.
TDI/ RSI*	IN	JTAG Data In/Ram Init. Serial Data In. Tie to VCC if unused. Connect to Serial EPROM data for RAM init.
TDO/ RCO*	OUT	JTAG Data Out/Ram Init Clock. Leave unconnected if unused. Connect to Serial EPROM clock for RAM init.
TCK	IN	JTAG Clock. Tie to GND if unused.
TMS	IN	JTAG Test Mode Select. Tie to VCC if unused.
TRSTB/ RRO*	IN	JTAG Reset/RAM Init. Reset Out. Tie to GND if unused. Connect to Serial EPROM reset for RAM init.
STM	IN	QuickLogic Reserved pin. Tie to GND on the PCB.

\*See QuickNote 65 on the QuickLogic web site for information on RAM initialization.



## PQFP 208 PINOUT TABLE

208	Function	208	Function	208	Function	208	Function	208	Function
PQFP		PQFP		PQFP		PQFP		PQFP	
1	I/O	43	GND	85	TxOut[4]	127	GND	169	I/O
2	I/O	44	I/O	86	TxOut[5]	128	I/O	170	I/O
3	I/O	45	I/O	87	TxOut[6]	129	GLCK/I	171	I/O
4	I/O	46	I/O	88	TxOut[7]	130	ACLK/I	172	I/O
5	I/O	47	I/O	89	TxOut[8]	131	VCC	173	I/O
6	I/O	48	I/O	90	TxOut[9]	132	ResIn[1]	174	I/O
7	I/O	49	I/O	91	TxOut[10]	133	ResIn[2]	175	I/O
8	I/O	50	I/O	92	TxOut[11]	134	VCC	176	I/O
9	I/O	51	I/O	93	TxOut[12]	135	I/O	177	GND
10	VCC	52	I/O	94	TxOut[13]	136	I/O	178	I/O
11	I/O	53	I/O	95	GND	137	I/O	179	I/O
12	GND	54	TDI	96	TxOut[14]	138	I/O	180	I/O
13	I/O	55	RxComDet	97	VCC	139	I/O	181	I/O
14	I/O	56	RxIn[0]	98	TxOut[15]	140	I/O	182	GND
15	I/O	57	RxIn[1]	99	TxOut[16]	141	I/O	183	I/O
16	I/O	58	RxIn[2]	100	TxOut[17]	142	I/O	184	I/O
17	I/O	59	GND	101	TxOut[18]	143	I/O	185	I/O
18	I/O	60	RxIn[3]	102	TxOut[19]	144	I/O	186	I/O
19	I/O	61	VCC	103	TRSTB	145	VCC	187	VCCIO
20	I/O	62	RxIn[4]	104	TMS	146	I/O	188	I/O
21	I/O	63	RxIn[5]	105	I/O	147	GND	189	I/O
22	I/O	64	RxIn[6]	106	I/O	148	I/O	190	I/O
23	GND	65	RxIn[7]	107	I/O	149	I/O	191	I/O
24	I/O	66	RxIn[8]	108	I/O	150	I/O	192	I/O
25	ResIn[0]	67	RxIn[9]	109	I/O	151	I/O	193	I/O
26	TxClk125_in	68	RxIn[10]	110	I/O	152	I/O	194	I/O
27	VCC	69	RxIn[11]	111	I/O	153	I/O	195	I/O
28	Rst	70	RxIn[12]	112	I/O	154	I/O	196	I/O
29	RxClk125_in	71	RxIn[13]	113	I/O	155	I/O	197	I/O
30	VCC	72	RxIn[14]	114	VCC	156	I/O	198	I/O
31	I/O	73	GND	115	I/O	157	TCK	199	GND
32	I/O	74	RxIn[15]	116	GND	158	STM	200	I/O
33	I/O	75	RxIn[16]	117	I/O	159	I/O	201	VCC
34	I/O	76	RxIn[17]	118	I/O	160	I/O	202	I/O
35	I/O	77	RxIn[18]	119	I/O	161	I/O	203	I/O
36	I/O	78	GND	120	I/O	162	I/O	204	I/O
37	I/O	79	RxIn[19]	121	I/O	163	GND	205	I/O
38	I/O	80	TxOut[0]	122	I/O	164	I/O	206	I/O
39	I/O	81	TxOut[1]	123	I/O	165	VCC	207	TDO
40	I/O	82	TxOut[2]	124	I/O	166	I/O	208	I/O
41	VCC	83	VCCIO	125	I/O	167	I/O		
42	I/O	84	TxOut[3]	126	I/O	168	I/O	1	



## PBGA 456 PINOUT TABLE

456	Function	456	Function	456	Function	456	Function	456	Function
A1	I/O	B26	STM	D25	I/O	H4	I/O	M14	GND/THERM
A2	I/O	C1	I/O	D26	I/O	H5	NC	M15	GND/THERM
A3	I/O	C2	I/O	E1	I/O	H22	NC	M16	GND/THERM
A4	I/O	СЗ	I/O	E2	I/O	H23	I/O	M22	NC
A5	I/O	C4	TDO	E3	I/O	H24	I/O	M23	NC
A6	I/O	C5	I/O	E4	I/O	H25	I/O	M24	I/O
A7	I/O	C6	I/O	E5	GND	H26	I/O	M25	I/O
A8	I/O	C7	I/O	E6	VCC	J1	I/O	M26	I/O
A9	I/O	C8	I/O	E7	GND	J2	I/O	N1	Async_rst
A10	I/O	C9	I/O	E8	NC	J3	I/O	N2	I/O
A11	I/O	C10	I/O	E9	GND	J4	NC	N3	I/O
A12	VCCIO	C11	I/O	E10	I/O	J5	GND	N4	ResIn[0]
A13	I/O	C12	I/O	E11	GND	J22	NC	N5	VCC
A14	I/O	C13	I/O	E12	GND	J23	NC	N11	GND/THERM
A15	I/O	C14	I/O	E13	VCC	J24	I/O	N12	GND/THERM
A16	I/O	C15	I/O	E14	GND	J25	I/O	N13	GND/THERM
A17	I/O	C16	I/O	E15	GND	J26	I/O	N14	GND/THERM
A18	I/O	C17	I/O	E16	GND	K1	I/O	N15	GND/THERM
A19	I/O	C18	I/O	E17	NC	K2	I/O	N16	GND/THERM
A20	I/O	C19	I/O	E18	GND	K3	I/O	N22	GND
A21	I/O	C20	I/O	E19	NC	K4	I/O	N23	I/O
A22	I/O	C21	I/O	E20	GND	K5	VCC	N24	I/O
A23	I/O	C22	I/O	E21	VCC	K22	GND	N25	I/O
A24	I/O	C23	I/O	E22	GND	K23	I/O	N26	I/O
A25	I/O	C24	I/O	E23	I/O	K24	I/O	P1	I/O
A26	I/O	C25	TCK	E24	I/O	K25	I/O	P2	I/O
B1	I/O	C26	I/O	E25	I/O	K26	I/O	P3	I/O
B2	I/O	D1	I/O	E26	I/O	L1	I/O	P4	I/O
B3	I/O	D2	I/O	F1	I/O	L2	I/O	P5	NC
B4	I/O	D3	I/O	F2	I/O	L3	I/O	P11	GND/THERM
B5	I/O	D4	GND	F3	I/O	L4	I/O	P12	GND/THERM
B6	I/O	D5	I/O	F4	NC	L5	NC	P13	GND/THERM
B7	I/O	D6	NC	F5	VCC	L11	GND/THERM	P14	GND/THERM
B8	I/O	D7	I/O	F22	VCC	L12	GND/THERM	P15	GND/THERM
B9	I/O	D8	I/O	F23	NC	L12	GND/THERM	P16	GND/THERM GND/THERM
B10	I/O	D9	GND	F24	I/O	L13	GND/THERM	P22	NC
B10	I/O	D10	I/O	F25	I/O	L15	GND/THERM GND/THERM	P23	ResIn[1]
B12	I/O		I/O	F26	I/O	L15	·	P24	
B13	I/O	D11 D12	GND	G1	I/O	L16	GND/THERM NC	P24 P25	ResIn[2] I/O
B14 B15	I/O I/O	D13	I/O I/O	G2 G3	I/O I/O	L23 L24	I/O I/O	P26	ACLK / I I/O
		D14						R1 R2	
B16	I/O	D15	GND	G4	I/O NG	L25	I/O I/O		I/O
B17	I/O	D16	I/O	G5	NC CND	L26		R3	I/O
B18	I/O	D17	I/O	G22	GND	M1 M2	TxClk125_in	R4	NC NC
B19	I/O	D18	GND	G23	I/O		RxClk125_in	R5	NC CND (THERM
B20	I/O	D19	I/O	G24	I/O	M3	I/O	R11	GND/THERM
B21	I/O	D20	I/O	G25	I/O	M4	NC	R12	GND/THERM
B22	I/O	D21	NC L(C	G26	I/O	M5	GND	R13	GND/THERM
B23	I/O	D22	I/O	H1	I/O	M11	GND/THERM	R14	GND/THERM
B24	I/O	D23	GND	H2	I/O	M12	GND/THERM	R15	GND/THERM
B25	I/O	D24	I/O	НЗ	I/O	M13	GND/THERM	R16	GND/THERM



456	Function	456	Function	456	Function	456	Function
R22	VCC	Y1	I/O	AC6	NC	AE5	RxIn[3]
R23	NC	Y2	I/O	AC7	I/O	AE6	RxIn[4]
R24	I/O	Y3	I/O	AC8	I/O	AE7	RxIn[5]
R25	I/O	Y4	I/O	AC9	NC	AE8	RxIn[6]
R26	GCLK / I	Y5	I/O	AC10	I/O	AE9	RxIn[7]
T1	I/O	Y22	GND	AC11	I/O	AE10	RxIn[8]
T2	I/O	Y23	I/O	AC12	NC	AE11	RxIn[9]
Т3	I/O	Y24	I/O	AC13	I/O	AE12	I/O
T4	I/O	Y25	I/O	AC14	VCCIO	AE13	TxOut[0]
T5	VCC	Y26	I/O	AC15	NC	AE14	TxOut[2]
T11	GND/THERMAL	AA1	I/O	AC16	I/O	AE15	TxOut[4]
T12	GND/THERMAL	AA2	I/O	AC17	I/O	AE16	TxOut[6]
T13	GND/THERMAL	AA3	NC	AC18	NC	AE17	TxOut[8]
T14	GND/THERMAL	AA4	NC	AC19	I/O	AE18	TxOut[10]
T15	GND/THERMAL	AA5	VCC	AC20	I/O	AE19	TxOut[12]
T16	GND/THERMAL	AA22	VCC	AC21	I/O	AE20	TxOut[14]
T22	GND	AA23	NC	AC22	NC	AE21	TxOut[16]
T23	I/O	AA24	I/O	AC23	GND	AE22	TxOut[18]
T24	I/O	AA25	I/O	AC24	I/O	AE23	NC
T25	I/O	AA26	I/O	AC25	I/O	AE24	TMS
T26	I/O	AB1	I/O	AC26	I/O	AE25	I/O
U1	I/O	AB2	I/O	AD1	I/O	AE26	I/O
U2	I/O	AB3	I/O	AD2	NC	AF1	I/O
U3	I/O	AB4	I/O	AD3	I/O	AF2	I/O
U4	I/O	AB5	GND	AD4	I/O	AF3	RxIn[10]
U5	GND	AB6	VCC	AD5	I/O	AF4	RxIn[11]
U22	NC	AB7	NC	AD6	I/O	AF5	RxIn[12]
U23	I/O	AB8	NC	AD7	I/O	AF6	RxIn[13]
U24	I/O	AB9	NC	AD8	I/O	AF7	RxIn[14]
U25	I/O	AB10	VCC	AD9	I/O	AF8	RxIn[15]
U26	I/O	AB11	GND	AD10	I/O	AF9	RxIn[16]
V1	I/O	AB12	NC	AD11	I/O	AF10	RxIn[17]
V2	I/O	AB13	I/O	AD12	RxComDet	AF11	RxIn[18]
V3	I/O	AB14	GND	AD13	I/O	AF12	RxIn[19]
V4	NC	AB15	VCC	AD14	I/O	AF13	TxOut[1]
V5	NC	AB16	I/O	AD15	I/O	AF14	TxOut[3]
V22	GND	AB17	NC	AD16	I/O	AF15	TxOut[5]
V23	NC	AB18	VCC	AD17	I/O	AF16	TxOut[7]
V24	I/O	AB19	GND	AD18	I/O	AF17	TxOut[9]
V25	I/O	AB20	NC	AD19	I/O	AF18	TxOut[11]
V26	I/O	AB21	VCC	AD20	I/O	AF19	TxOut[13]
W1	I/O	AB22	GND	AD21	I/O	AF20	TxOut[15]
W2	I/O	AB23	I/O	AD22	I/O	AF21	TxOut[17]
W3	I/O	AB24	I/O	AD23	TRSTB	AF22	TxOut[19]
W4	I/O	AB25	I/O	AD24	I/O	AF23	I/O
W5	NC	AB26	I/O	AD25	I/O	AF24	I/O
W22	NC L(C)	AC1	I/O	AD26	I/O	AF25	I/O
W23	I/O	AC2	I/O	AE1	TDI	AF26	I/O
W24	I/O	AC3	NC	AE2	RxIn[0]		
W25	I/O	AC4	GND	AE3	RxIn[1]		
W26	I/O	AC5	I/O	AE4	RxIn[2]		



## TIMING DIAGRAMS

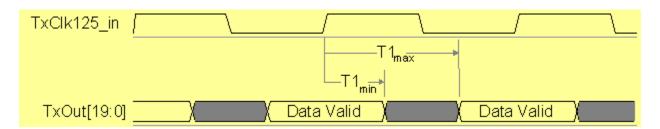


FIGURE 7. Transmit Timing Diagram

## **Transmit Timing Characteristics**

Parameter	Description	Min	Тур	Max	Units
T1	Clock to Out	2.5	3.7	5.6	ns

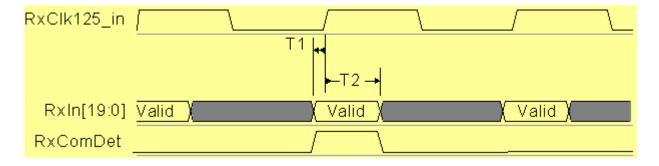


FIGURE 8. Receive Timing Diagram

## **Receive Timing Characteristics**

Parameter	Description	Min	Тур	Max	Units
T1	Setup time	0.0			ns
T2	Hold time	2.3	1.5		ns



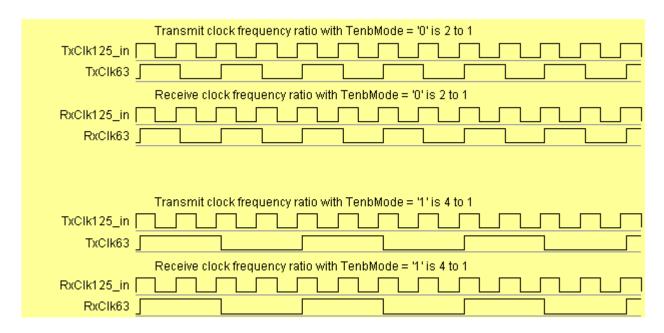


FIGURE 9. Clock Frequency Ratios are Dependent on tenbMode setting



#### REFERENCE DEVELOPMENT KIT

QuickLogic has designed an evaluation board, which will allow the system designer to test their designs in hardware. The board plugs into a PCI expansion slot in a Windows PC and allows the user to communicate with the QuickLogic ENDEC chip via a user modifiable software script and the PCI bus. The block diagram for the board is shown below. PCI speeds of up to 64 bits at 75 MHz are supported via QuickLogic's QL5064 device, enabling system read/write speeds matching those of the Fibre Channel link. There is a socket for the ENDEC chip, and connection points for a logic analyzer on the board. There is

also a GBIC Fibre Channel connector on the board to allow communication with other Fibre Channel devices.

A Reference Design is supplied by QuickLogic to load into the programmable portion of the ENDEC chip. The Reference Design code will allow the system designer to immediately have an operational chip for use on the reference board. The source code for the reference design and software is available to the system designer for use or modification as he or she wishes, free of charge.

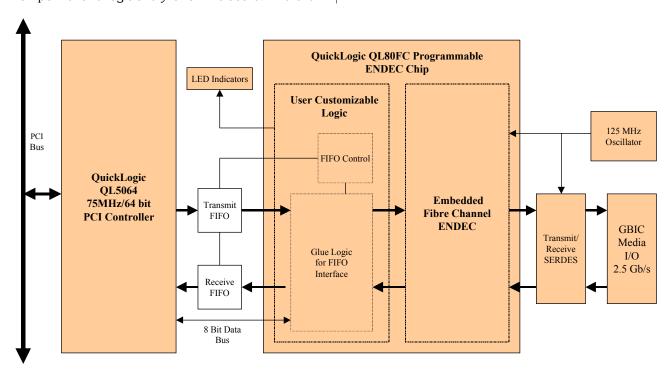


FIGURE 10. Reference Board Block Diagram



## **Absolute Maximum Ratings**

VCC Voltage0.5 to 4.6V	DC Input Current ±20 mA
VCCIO Voltage0.5 to 7.0V	ESD Pad Protection ±2000V
Input Voltage0.5V to VCCIO +0.5V	Storage Temperature65°C to + 150°C
Latch-up Immunity $\pm 200$ mA	Lead Temperature 300°C

## **Operating Range**

Symbol	Para	meter	Industrial		Comm	ercial	Unit
			Min	Max	Min	Max	
VCC	Supply Voltage		3.0	3.6	3.0	3.6	V
VCCIO	I/O Input Tolerance Voltage		3.0	5.5	3.0	5.25	V
TA	Ambient Temperature		-40	85	0	70	°C
K	Delay Factor	-A Speed Grade	0.43	0.90	0.46	0.88	

#### **DC Characteristics**

Symbol	Parameter	Conditions	Min	Max	Unit
VĬH	Input HIGH Voltage		0.5VCC	VCCIO+0.5	V
VIL	Input LOW Voltage		-0.5	0.3VCC	V
VOH	Output HIGH Voltage	IOH = -12 mA	2.4		V
	·	IOH = -500 μA	0.9VCC		V
VOL	Output LOW Voltage	IOL = 16 mA		0.45	V
	-	IOL = 1.5 mA		0.1VCC	V
II	I or I/O Input Leakage Current	VI = VCCIO or GND	-10	10	μд
IOZ	3-State Output Leakage Current	VI = VCCIO or GND	-10	10	μд
CI	Input Capacitance [1]			10	рF
IOS	Output Short Circuit Current [2]	VO = GND	-15	-180	mΑ
		VO = VCC	40	210	mA
ICC	D.C. Supply Current [3]	VI, VIO = VCCIO or GND	0.50 (typ)	2	mA
ICCIO	D.C. Supply Current on VCCIO		0	100	μΑ

#### Notes:

- [1] Capacitance is sample tested only.
- [2] Only one output at a time. Duration should not exceed 30 seconds.
- [3] See Application Note 32: Power calculations for QuickLogic devices.



#### AC CHARACTERISTICS at VCC = 3.3V, TA = 25°C (K = 1.00)

(To calculate delays, multiply the appropriate K factor in the "Operating Range" section by the following numbers.)

#### **Logic Cells**

Symbol	Parameter	Propagation Delays (ns) Fanout [5]							
		1	2	3	4	8			
tPD	Combinatorial Delay [6]	1.4	1.7	1.9	2.2	3.2			
tSU	Setup Time [6]	1.7	1.7	1.7	1.7	1.7			
tH	Hold Time	0.0	0.0	0.0	0.0	0.0			
tCLK	Clock to Q Delay	0.7	1.0	1.2	1.5	2.5			
tCWHI	Clock High Time	1.2	1.2	1.2	1.2	1.2			
tCWLO	Clock Low Time	1.2	1.2	1.2	1.2	1.2			
tSET	Set Delay	1.0	1.3	1.5	1.8	2.8			
tRESET	Reset Delay	0.8	1.1	1.3	1.6	2.6			
tSW	Set Width	1.9	1.9	1.9	1.9	1.9			
tRW	Reset Width	1.8	1.8	1.8	1.8	1.8			

#### **RAM Cell Synchronous Write Timing**

Symbol	Parameter	Propagation Delays (ns) Fanout [4]							
		1	2	3	4	8			
TSWA	WA Setup Time to WCLK	1.0	1.0	1.0	1.0	1.0			
THWA	WA Hold Time to WCLK	0.0	0.0	0.0	0.0	0.0			
TSWD	WD Setup Time to WCLK	1.0	1.0	1.0	1.0	1.0			
THWD	WD Hold Time to WCLK	0.0	0.0	0.0	0.0	0.0			
TSWE	WE Setup Time to WCLK	1.0	1.0	1.0	1.0	1.0			
THWE	WE Hold Time to WCLK	0.0	0.0	0.0	0.0	0.0			
TWCRD	WCLK to RD (WA=RA) [4]	5.0	5.3	5.6	5.9	7.1			

#### Notes:

- [4] Stated timing for worst case Propagation Delay over process variation at VCC=3.3V and TA=25°C. Multiply by the appropriate Delay Factor, K, for speed grade, voltage and temperature settings as specified in the Operating Range.
- [5] These limits are derived from a representative selection of the slowest paths through the QuickRAM logic cell including typical net delays. Worst case delay values for specific paths should be determined from timing analysis of your particular design.



#### **RAM Cell Synchronous Read Timing**

Symbol	Parameter	Propagation Delays (ns) Fanout							
		1 2 3 4							
TSRA	RA Setup Time to RCLK	1.0	1.0	1.0	1.0	1.0			
THRA	RA Hold Time to RCLK	0.0	0.0	0.0	0.0	0.0			
TSRE	RE Setup Time to RCLK	1.0	1.0	1.0	1.0	1.0			
THRE	RE Hold Time to RCLK	0.0	0.0	0.0	0.0	0.0			
TRCRD	RCLK to RD [5]	4.0	4.3	4.6	4.9	6.1			

## **RAM Cell Asynchronous Read Timing**

Symbol	Parameter	Propagation Delays (ns) Fanout 1 2 3 4 8							
RPDRD	RA to RD [5]	3.0 3.3 3.6 3.9 5.1							

#### **Input-Only Cells**

Symbol	Parameter	Propagation Delays (ns) Fanout [5]							
		1	2	3	4	8	12	24	
TIN	High Drive Input Delay	1.5	1.6	1.8	1.9	2.4	2.9	4.4	
TINI	High Drive Input, Inverting Delay	1.6	1.7	1.9	2.0	2.5	3.0	4.5	
TISU	Input Register Set-Up Time	3.1	3.1	3.1	3.1	3.1	3.1	3.1	
TIH	Input Register Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	0.0	
TICLK	Input Register Clock To Q	0.7	8.0	1.0	1.1	1.6	2.1	3.6	
TIRST	Input Register Reset Delay	0.6	0.7	0.9	1.0	1.5	2.0	3.5	
TIESU	Input Register Clock Enable Setup Time	2.3	2.3	2.3	2.3	2.3	2.3	2.3	
TIEH	Input Register Clock Enable Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	0.0	

#### **Clock Cells**

Symbols	Parameter	Propagation Delays (ns) Loads per Half Column [6]							
		1	2	3	4	8	10	12	15
tACK	Array Clock Delay	1.2	1.2	1.3	1.3	1.5	1.6	1.7	1.8
tGCKP	Global Clock Pin Delay	0.7	0.7	0.7	0.7	0.7	0.7	0.7	0.7
tGCKB	Global Clock Buffer Delay	0.8	0.8	0.9	0.9	1.1	1.2	1.3	1.4

#### Notes:

[6] The array distributed networks consist of 40 half columns and the global distributed networks consist of 44 half columns, each driven by an independent buffer. The number of half columns used does not affect clock buffer delay. The array clock has up to 8 loads per half column. The global clock has up to 11 loads per half column.



## I/O Cell Input Delays

Symbol	Parameter	Propagation Delays (ns) Fanout [5]						
		1	2	3	4	8	10	
tI/O	Input Delay (bidirectional pad)	1.3	1.6	1.8	2.1	3.1	3.6	
TISU	Input Register Set-Up Time	3.1	3.1	3.1	3.1	3.1	3.1	
TIH	Input Register Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	
TIOCLK	Input Register Clock To Q	0.7	1.0	1.2	1.5	2.5	3.0	
TIORST	Input Register Reset Delay	0.6	0.9	1.1	1.4	2.4	2.9	
TIESU	Input Register clock Enable Set-Up Time	2.3	2.3	2.3	2.3	2.3	2.3	
TIEH	Input Register Clock Enable Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	

## I/O Cell Output Delays

Symbol	Parameter	C	Propagation Delays (ns) Output Load Capacitance (p					
		30	50	75	100	150		
TOUTLH	Output Delay Low to High	2.1	2.5	3.1	3.6	4.7		
TOUTHL	Output Delay High to Low	2.2	2.6	3.2	3.7	4.8		
TPZH	Output Delay Tri-state to High	1.2	1.7	2.2	2.8	3.9		
TPZL	Output Delay Tri-state to Low	1.6	2.0	2.6	3.1	4.2		
TPHZ	Output Delay High to Tri-State [8]	2.0						
TPLZ	Output Delay Low to Tri-State [8]	1.2						

#### Notes:

[7] The following loads are used for tPXZ:

